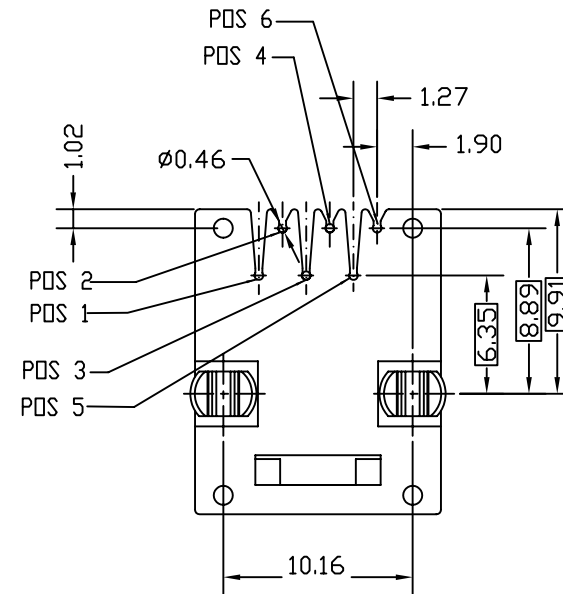
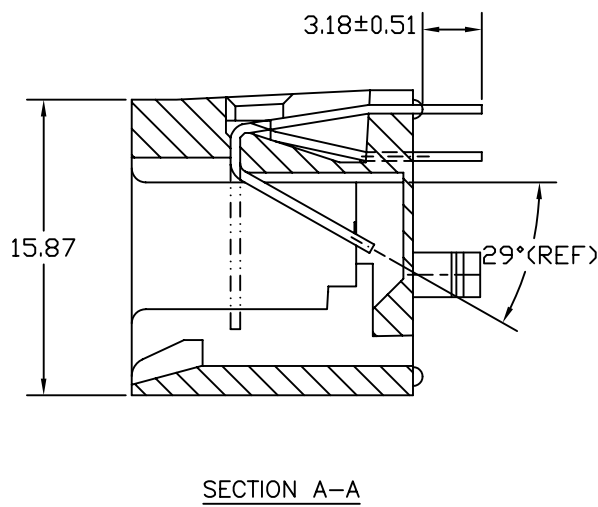
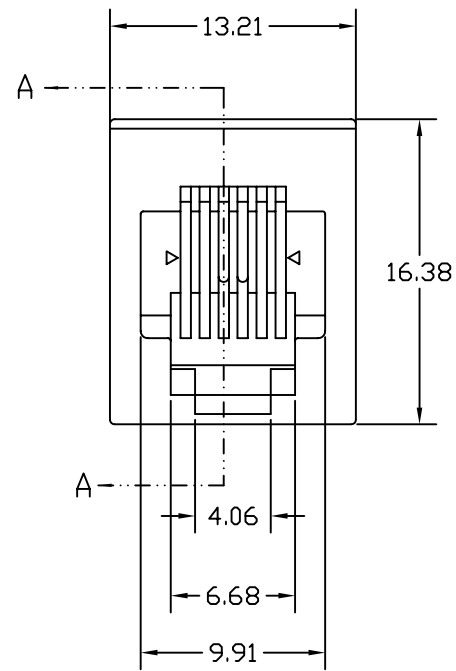
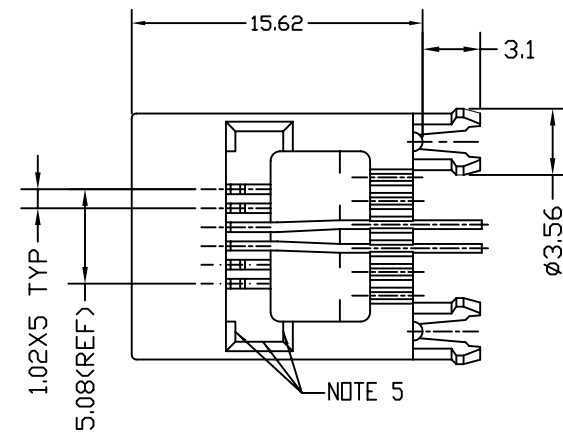


1.LF PRODUCTS MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.

2.THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 3.5 SEC IN A WAVE SOLDER APPLICATION WITH A 1.57mm MIN THICK CIRCUIT BOARD. SLIGHT DEFORMATION OF SNAP PEGS MAY OCCUR AT 260-265°C WHICH WILL NOT AFFECT THE FUNCTION OF THE PRODUCT.

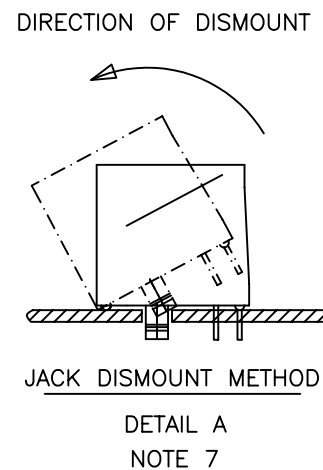
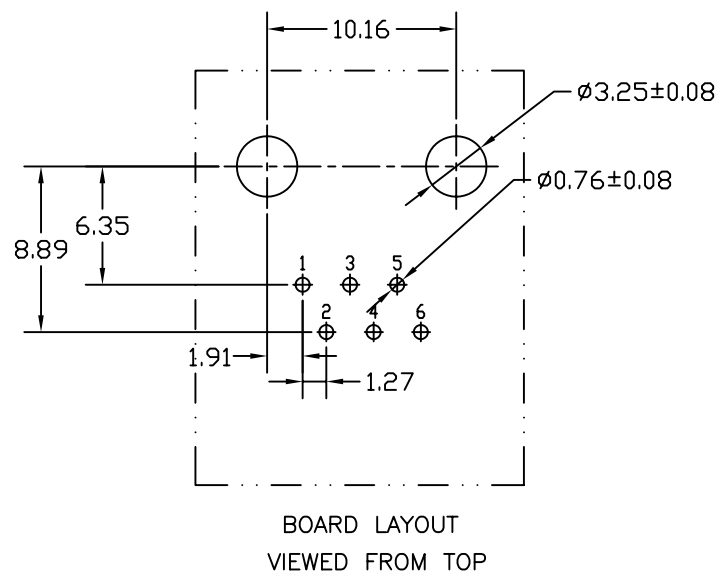
3.LEAD FREE OR ROHS DIRECTIVE LABELLING TO BE PROVIDED AS PER GS-14-920 FOR LEADFREE VERSION.



10037501 - X X 2 LF  
 LEAD FREE  
 POS LOADED  
 0 - 3&4  
 1 - 2,3,4&5  
 2 - ALL POS  
 CONTACT PLATING  
 0 - 30u" GXT  
 1 - 30u" GOLD

NOTES :

- INSULATOR MATERIAL -THERMOPLASTIC UL 94 V0 BLACK  
 HOUSING : NYLON 66 25% GLASS FILLED UL94 V0  
 THE HOUSING WILL WITHSTAND EXPOSURE TO 260-265°C FOR 3.5 SECONDS IN NORMAL WAVE SOLDERING APPLICATION. USE PROTECTIVE ADHESIVE(KAPTON OR TEFLON) OR PROTECTIVE METALLIC DEVICE ON THE AREAS WHICH ARE DIRECTLY EXPOSED TO WAVE SOLDERING AS IT IS USED IN CLASSICAL LEADED WAVE SOLDERING.
- CONTACT :  $\phi 0.46$ mm PHOSPHORBRONZE WIRE
- WIRE MUST BE CONTAINED WITHIN COMB SHELVES.
- PACKAGING IN TUBE
- SCRATCH MARKS ACCEPTABLE ON THESE SURFACES.
- JACK IS FOR 1,57mm THICK PCB.
- SHOULD THE JACK NEED TO BE DISMOUNTED FROM THE PCB, PLS REMOVE JACK AS PER RECOMMENDED METHOD HEREIN. (DETAIL A) NIPPING THE LEGS OF THE PEG TOGETHER IS DISALLOWED, OTHERWISE LEG BREAKAGE MAY OCCUR.



mat'l. code SEE NOTES 1 & 2		surface ISO 1302 ✓		tolerance ISO 406 ISO 1101		projection MM		product family MODJACK	
ltr		ecn no		dr		date		title	
B		I08-0157		NPM		2009-04-06		6 POS VER MOD JACK WITH SNAP PEGS	
C		I09-0083		NPM		2009-05-21			
sheet index		revision sheet		c				dwg no 10037501	
								sheet 1 of 1	
								size A4	
								type Product Customer Drawing	